



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-06-03
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Emilio Castelli	Representative Title	APG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
FDA2100LV	A6DE*UI21ADA	A	MU1A	2013-06-03
Amount		UoM	Unit type	ST ECOPACK Grade
260.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used	ium/Gold (Ni/Pd/Au) Tin/Bismuth (S	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	10X10X1.0	64	flat	
Comment				

Material Composition Declaration						Mfr Item Name	A6DE*UI21ADA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	16.242	mg	supplier	die	Silicon (Si)	7440-21-3		15.386	mg	947297	59177
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.158	mg	9728	608
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.158	mg	9728	608
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.096	mg	5911	369
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.033	mg	2032	127
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.27	mg	16624	1038
die (s)				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.012	mg	739	46
die (s)				supplier	back side metallization	Gold (Au)	7440-57-5		0.031	mg	1909	119
die (s)				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.091	mg	5603	350
die (s)				supplier	back side metallization	Vanadium (V)	7440-62-2		0.007	mg	431	27
Leadframe	Copper & its alloys	28.993	mg	supplier	alloy	Copper (Cu)	7440-50-8		27.892	mg	962025	107277
Leadframe				supplier	alloy	Nickel (Ni)	7440-02-0		0.87	mg	30007	3346
Leadframe				supplier	alloy	Magnesium (Mg)	7439-95-4		0.043	mg	1483	165
Leadframe				supplier	alloy	Silicon (Si)	7440-21-3		0.188	mg	6484	723
Die attach		3.679	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		2.943	mg	799946	11319
Die attach				supplier	glue or tape	epoxy resin	Proprietary		0.589	mg	160098	2265
Die attach				supplier	glue or tape	aromatique amine	0		0.11	mg	29899	423
Die attach				supplier	glue or tape	Epoxyde Bisphenol A Resin	25068-38-6		0.037	mg	10057	142
Bonding wire		5.96		supplier	wire	Gold (Au)	7440-57-5		5.9	mg	989933	22692
Bonding wire				supplier	wire	Palladium (Pd)	7440-05-3		0.06	mg	10067	231
encapsulation		205.126	mg	supplier	mold compound	Epoxy Resin	85954-11-6		16.41	mg	80000	63115
encapsulation				supplier	mold compound	Phenol Resin	26834-02-6		8.205	mg	40000	31558
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		178.665	mg	871001	687173
encapsulation				supplier	mold compound	Carbon black	1333-86-4		1.026	mg	5002	3946
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.82	mg	3998	3154